

dicing width smaller than the diced groove of the semiconductor wafer.

15. A method of manufacturing a semiconductor device, comprising the steps of:

5 shaving a back surface of a semiconductor wafer, the back surface being opposite to an electrode-formed surface of the semiconductor wafer which includes a plurality of semiconductor elements;

dividing the semiconductor wafer into the semiconductor elements; and

10 bonding a reinforcing member to a back surface of each of the semiconductor elements with an adhesive.

16. The method of claim 15, further comprising the step of attaching a sheet to the electrode-formed surface of the semiconductor wafer, wherein said step of shaving the back surface of the semiconductor wafer includes the sub  
15 step of shaving the back surface of the semiconductor wafer to which the sheet is attached.

17. The method of claim 15, further comprising the step of forming a bump on the electrode-formed surface of the semiconductor wafer.

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18. A method of mounting a semiconductor device which includes:

a semiconductor element having an electrode-formed surface;

a reinforcing member bonded to a back surface of the semiconductor element with allowing the semiconductor element to be deformed, the back  
25 surface being opposite the electrode-formed surface; and

an adhesive bonding the semiconductor element to the reinforcing member,

holding the reinforcing member; and

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wherein the reinforcing member includes a recess portion to which the semiconductor element is bonded and a projection formed at a border of the recess portion, and

10 wherein said step of mounting the semiconductor device includes the  
sub step of bonding the projection to the workpiece.

**THE**